

ARGUMENTS

Claim 1-4 are rejected under 35 U.S.C 102(b) as being unpatentable by Chang (US 6,232,551).

Applicant thinks that it is true that Chang does not disclose the resistant
5 layer 42 is coated on the lower surface of the substrate 40, and is located between the long slot 56 and wires region 58.

Therefore, the invention has the following advantages.

1. Since if the flowed glue of the glue layer 44 is flowed to the lower surface 54 of the substrate 40 through the long slot 56, the flowed
10 glue can be prevented by the resistant layer 42 to flow to the wiring regions 58. Thus, the connected points 60 do not covered by the flowed glue.

2. Since the length of the wiring regions 58 are shorter than the long slot 56, so that, while drilled the long slot 56, if the substrate 40 is
15 cracked, which is can be not coupled to the wiring regions 58. Thus the connected points 60 can be not covered by the flowed glue of the glue layer 44

Thus, the 551, patent does not disclose a similar structure of that this application, and does not motivate the Applicant to finish the application.
20 Reconsideration of claim 1- 4 is politely requested.

In light of the above remarks, Applicant now asserts that all of the grounds

for rejection have been traversed or overcome by the detailed arguments, and that all of the present claims are in condition for immediate allowance. Applicant therefore requests reconsideration of the rejections, and solicits allowance of the present claims at an early date.

5 Thank you for your consideration.

Respectfully submitted,

Date: 4/11/2006 Jichen WU

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10 the Assignee of this application

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